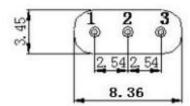
SPECIFICATION

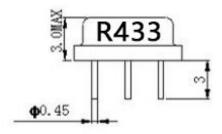
CUSTOMER:			
PRODUCT :	声表谐振器		
MODEL NO:	LT-SR-433-D11		
PREPARED:	杨嘉妮CHECK	ED:顾杰	
DATE:	2022-03-10		
	Citi Ina		
CUSTOMER RECE	IVED:		
CHECKED	APPROVED	DATE	

版本说明

日期	版本号	修订说明	拟制	审核
2022-03-10	1.0	初版	杨嘉妮	顾杰
			<u> </u>	
			Sheet	
		DE	Oglo	
		Codan va		
	SI	citilina		

1. Package Dimension (D-11)

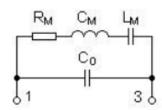


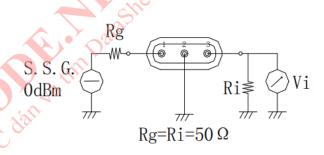


Pin	Connection	
1	Input/Output	
2	Case Ground	
3	Output/ Input	

Marking			
R SAW resonator			
R433	Center Frequency		

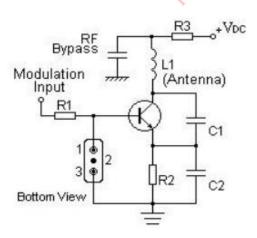
2. Equivalent LC Model and Test Circuit



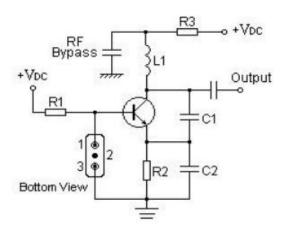


3. Typical Application Circuit

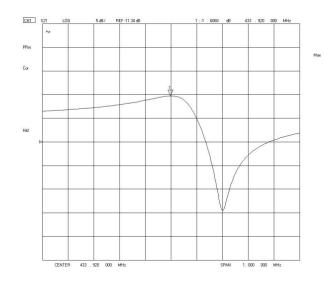
1) Typical Low-Power Transmitter Application



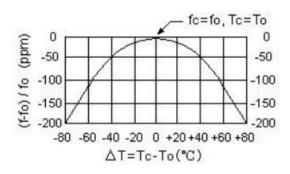
2) Typical Local Oscillator Application



4. Typical Frequency Response



5.Temperature Characteristics



6. Performance

6-1. Maximum Rating

Rating	Value	Units	
CW RF Power Dissipation	+10	dBm	
DC Voltage Between Any Two Pins	±10V	VDC	
Operation Temperature	-40 to +85	°C	
Storage Temperature	-55 to +125	°C	

6-2.Electronic Characteristics

	Characteristic	Sym	Minimum	Typical	Maximum	Units
Center Frequency	Absolute Frequency	f_C		433.92		MHz
(+25°C)	Tolerance from 433.92MHz	$\triangle f_{C}$		±75		kHz
Insertion Loss		IL		1.4	2.0	dB
Quality Factor	Unloaded Q	Q_U		14215		
Quality Factor	50 Ω Loaded Q	Q_L		1791		
Tommonotumo	Turnover Temperature	To	10	25	40	°C
Temperature Stability	Turnover Frequency	f_{O}		fc		kHz
	Frequency Temperature Coefficient	FTC		0.032		ppm/°C²
Frequency Aging Absolute Value during the First Year		$ f_A $		≤10		ppm/yr
DC Insulation Resistance Between Any Two Pins			1.0			ΜΩ
	Motional Resistance	R_{M}		15	26	Ω
RF Equivalent RLC	Motional Inductance	L_{M}		98.9		μΗ
Model	Motional Capacitance	C_{M}		2.35		fF
	Pin 1 to Pin 3 Static Capacitance	C _o	2.8	3.1	3.4	pF

CAUTION: Electrostatic Sensitive Device. Observe precautions for handling!

Notes:

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to ESD protect in the test.

- 2. Static voltage between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
- 3. Ultrasonic cleaning may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
- 4. Only leads of component may be soldered. Please avoid soldering another part of component.
- 5. There is a close relationship between the device's performance and matching network. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.

